

REMARKS

Attached hereto is a marked-up version of the changes made to the claims by the current Amendment. The attached is captioned "**Version with markings to show changes made**".

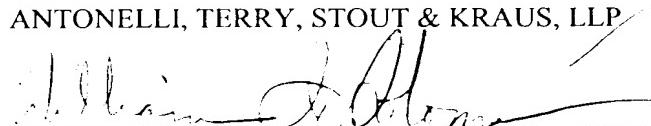
Applicants have amended their claims, prior to examination of the above-identified application, to correct typographical and grammatical errors, and to further clarify the definition of various aspects of the present invention. With respect to these amendments to the claims, note, for example, the examples in the above-identified application, beginning at page 15 of the Applicants' specification.

Entry of the present Preliminary Amendment and examination of the above-identified application in due course, are respectfully requested.

Please charge any shortage in fees due in connection with the filing of this paper, or credit any overpayment of fees, to the deposit account of Antonelli, Terry, Stout & Kraus, LLP, Deposit Account No. 01-2135 (511.41182X00).

Respectfully submitted,

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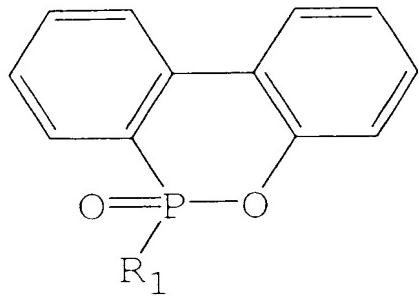


VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS

Please amend the claims as follows:

1. (Amended) A resin composition comprising:
 - an epoxy resin,
 - an amine-type curing agent,
 - an organophosphorous compound having a structure represented by formula 1:



Formula 1

Wherein R1 is an aryl radical with two hydroxyl groups, and the aryl radical can be substituted by one to three lower alkyls, and
an organic solvent,

wherein the epoxy resin and the organophosphorous compound have been compounded at a temperature of 50°C or lower.

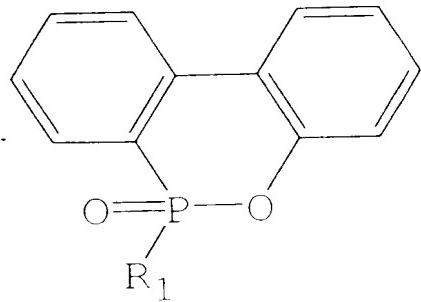
8. (Amended) The resin composition according to claim 7, wherein the inorganic filler is aluminum hydroxide.

10. (Amended) A prepreg obtained by impregnating a substrate with the resin composition according to any one of claims 1 to 9 and then drying the substrate impregnated with the resin composition.

11. (Amended) A laminate comprising ~~the~~ at least one prepreg according to claim 10 and a ~~at least one~~ metal foil.

12. (Amended) A printed wiring plate wherein the resin composition according to any one of claims 1 to 9 is used as an insulating material substrate.

13. (Amended) A method for producing a resin composition comprising:
an epoxy resin,
an amine-type curing agent,
an organophosphorous compound having a structure represented by formula 1:



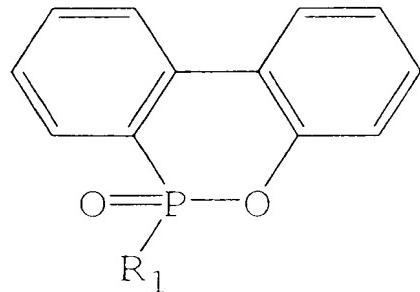
Formula 1

Wherein R4 wherein R_1 is an aryl radical with two hydroxyl groups, and the aryl radical can be substituted by one to three lower alkyls, and

an organic solvent,

wherein the epoxy resin and the organophosphorous compound are compounded at a temperature of 50°C or lower.

14. (Amended) A method for producing a resin composition comprising:
- an epoxy resin,
 - an amine-type curing agent,
 - an organophosphorous compound having a structure represented by formula 1:



Formula 1

Wherein R4 wherein R_1 is an aryl radical with two hydroxyl groups, and the aryl radical can be substituted by one to three lower alkyls, and

an organic solvent,

the method comprising:

allowing the epoxy resin and the amine-type curing agent to react in ~~in~~ the organic solvent at a temperature of from 80 to 140°C,

whereby bringing the two components into a state where the two components are mutually compatible in the absence of a solvent, and then

compounding the organophosphorus compound to the reaction product at a temperature of 50°C or lower.

17. (Amended) A method producing a laminate, the method comprising arranging a at least one metal foil on ~~the~~ at least one prepreg prepared by the method according to claim 16, and heating and pressurizing them to laminate together.